PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15369878

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DATE SIGNED:	12/06/2016

Total Attachments: 11
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Declaration (37 CFR 1.63) for Utility Patent Application Using An Application Data Sheet (37 CFR 1.76) and Assignment For Single Assignee

The title of the invention is as follow:

FABRICATING METHOD OF SEMICONDUCTOR STRUCTURE

As a below named inventor, I hereby declare that this declaration is directed to the application of which is attached hereto unless the following box is checked:

☐ was filed on ______________ as United States Application Number or PCT International Application Number ______________________

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

WHEREAS, United Microelectronics Corporation (hereinafter referred to "Assignee") whose mailing address is NO. 3, LI-HSIN RD. II, SCIENCE-BASED INDUSTRIAL PARK, HSINCHU, TAIWAN is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

Now, therefore, in consideration of the sum of One dollars ($ 1.00), the receipt whereof is acknowledged, and for other good and valuable consideration, I, by these presents hereby do sell, assign and transfer unto said Assignee the entire right, title, and interest in and to any and all improvements which are disclosed in said invention and, in and to, all Letters Patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all continuations, continuation-in-part, divisions, renewals, substitutions, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said Assignee as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of said Assignee, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me had this Assignment and sale not been made.

Further, I agree that I will communicate to said Assignee or its (his) representatives any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said Assignee, make all rightful oaths, and, generally do everything possible to aid said Assignee, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

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☐ Additional inventors are being named on the next page, if any